



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No. : 10/734,195
Applicant : Kwun-Yao Ho et al.
Filed : December 15, 2003
Title : HIGH-DENSITY MULTICHIP MODULE
PACKAGE
TC/A.U. : 2813
Examiner : BRYANT, DELORIS S
Docket No. : 025796-00014

RESPONSE UNDER 37 C.F.R. § 1.111

MAIL STOP AMENDMENT

Commissioner for Patents

P.O. Box 1450

Alexandria, Virginia 22313-1450

October 6, 2006

Sir:

In reply to the Official Action dated June 29, 2006, the period for response being extended from September 29, 2006 to October 29, 2006, by the attached Petition for Extension of Time, please amend the above-identified application as set forth below:

Amendments to the Claims begin on page 2 of this paper.

Remarks begin on page 5 of this paper.